## IN THE CLAIMS-

Please amend the claims as follows:

Claims 1-10 (canceled)

11. (previously presented): An uncured panel assembly comprising a:

a core having a first and a second surface, said first and second surfaces being located on opposite sides of said core and defining the thickness of said core;

at least one uncured prepreg located on at least one of said first or second surfaces of said core, said uncured prepreg having an outer surface and an inner surface, said inner surface being adjacent to said core first or second surface and said uncured prepreg comprising a thermosetting resin that has a cure temperature; and

an uncured pigmented layer attached directly to the outer surface of said uncured prepreg, said uncured pigmented layer comprising:

an uncured pigmented binder resin, said uncured pigmented binder resin comprising an uncured thermoplastic resin and a pigment wherein said thermoplastic resin has a cure temperature that is equal to or less than the cure temperature of said uncured thermosetting resin present in said prepreg.

- 12. (original): An uncured panel assembly according to claim 11 wherein said core comprises honeycomb.
- 13. (previously presented): An uncured panel assembly according to claim 11 wherein said uncured thermoplastic resin present in said uncured pigmented binder is polyvinyl butyral.
- 14. (previously presented): An uncured panel assembly according to claim 11 wherein said uncured thermosetting resin present in said uncured prepreg is selected from the group consisting of phenolic resole, phenolic novalac and flame retardant epoxy.
- 15. (previously presented): An uncured panel assembly according to claim 11 which further comprises a substrate on which said pigmented binder resin is located, said substrate having a prepreg melting point that is above the cure temperature of said.

- 16. (previously presented): An uncured panel assembly according to claim 15 wherein said substrate comprises a textile substrate and/or a film substrate.
- 17. (previously presented): An uncured panel assembly according to claim **16** wherein said film substrate comprises polyethylene.
- 18. (currently amended): An uncured panel assembly according to claim <u>16</u> <u>15</u> wherein said textile substrate comprises a textile selected from the group consisting of glass fabric and polyester matt.
- 19. (previously presented): An uncured panel assembly according to claim 11 wherein said pigment comprises titanium dioxide.
- 20. (original): An uncured panel assembly according to claim 19 wherein said uncured thermoplastic resin present in said uncured pigmented binder comprises polyvinyl butyral, said uncured thermosetting resin present in said prepreg is selected from the group consisting of phenolic resole, phenolic novalac and flame retardant epoxy and said substrate comprises a thermoplastic film substrate comprising polyethylene terephthalate.
- 21. (previously presented): A panel assembly comprising an uncured panel assembly according to claim 11 that has been heated to a processing temperature that is equal to or above the cure temperature for said thermosetting resin for a sufficient time to cure both said thermosetting resin in said prepreg and said thermoplastic resin present in said pigmented binder.
- 22. (original): A method for making an uncured pigmented panel assembly, said method comprising the steps of:

providing a core having a first and a second surface, said first and second surfaces being located on opposite sides of said core and defining the thickness of said core;

locating at least one uncured prepreg on at least one of said first or second surfaces of said core, said uncured prepreg having an outer surface and an inner surface, said inner surface being located adjacent to said core first or second surface and said uncured prepreg comprising a thermosetting resin that has a cure temperature; and

- prepreg, said uncured pigmented layer comprising an uncured pigmented binder resin, said uncured pigmented binder resin comprising an uncured thermoplastic resin and a pigment wherein said thermoplastic resin has a cure temperature that is equal to or less than the cure temperature of said uncured thermosetting resin present in said prepreg.
- 23. (previously presented): A method for making an uncured pigmented panel assembly according to claim 22 wherein said uncured pigmented layer comprises a substrate on which said pigmented binder resin is located, said substrate having a melting point that is above the cure temperature of said prepreg.
- 24. (original): A method for making an uncured pigmented panel assembly according to claim 22 wherein said core comprises honeycomb.
- 25. (original): A method for making an uncured pigmented panel assembly according to claim 22 wherein said uncured thermoplastic resin present in said uncured pigmented binder is polyvinyl butyral.
- 26. (original): A method for making an uncured pigmented panel assembly according to claim 22 wherein said uncured thermosetting resin present in said uncured prepreg is selected from the group consisting of phenolic resole, phenolic novalac and flame retardant epoxy.
- 27. (original): A method for making an uncured panel assembly according to claim 23 in which said substrate comprises a textile substrate and/or a thermoplastic film substrate.
- 28. (original): A method for making an uncured panel assembly according to claim 27 wherein said substrate comprises a thermoplastic film substrate comprising polyethylene terephthalate.
- 29. (original): A method for making an uncured panel assembly according to claim 28 wherein said film comprising polyethylene terephthalate is between about 36 and 50 microns thick.

- 30. (previously presented): A method for making an uncured panel assembly according to claim 22 wherein said pigment comprises titanium dioxide.
- 31. (previously presented): A method for making an uncured panel assembly according to claim 27 wherein said pigment comprises titanium dioxide, said uncured thermoplastic resin present in said uncured pigmented binder comprises polyvinyl butyral, said uncured thermosetting resin present in said prepreg is selected from the group consisting of phenolic resole, phenolic novalac and flame retardant epoxy and said substrate comprises a thermoplastic film substrate comprising polyethylene terephthalate.
- 32. (original): A method according to claim 22 that includes the additional steps of heating said uncured panel assembly to a processing temperature that is equal to or above the cure temperature for said thermosetting resin for a sufficient time to cure both said thermosetting resin in said prepreg and said thermoplastic resin present in said pigmented binder to form a cured panel assembly.
- 33. (previously presented): A method according to claim 23 that includes the additional step of heating said uncured panel assembly to a processing temperature that is equal to or above the cure temperature for said thermosetting resin for a sufficient time to cure both said thermosetting resin in said prepreg and said thermoplastic resin present in said pigmented binder to form a cured panel assembly, wherein said processing temperature is below the melting point of said substrate.